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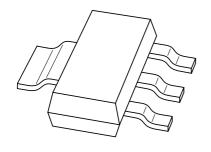
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Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



BSP130 N-channel enhancement mode vertical D-MOS transistor

Product specification Supersedes data of 1997 Jun 23 2001 Dec 11





N-channel enhancement mode vertical D-MOS transistor

BSP130

FEATURES

- Direct interface to C-MOS, TTL, etc.
- · High-speed switching
- No secondary breakdown.

APPLICATIONS

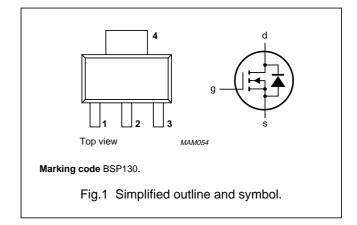
- Line current interruptor in telephone sets
- Relay, high-speed and line transformer drivers.

DESCRIPTION

N-channel enhancement mode vertical D-MOS transistor in a SOT223 package.

PINNING - SOT223

PIN	DESCRIPTION
1	gate
2	drain
3	source
4	drain



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DS}	drain-source voltage (DC)		_	300	V
I _D	drain current (DC)		_	350	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	_	1.5	W
V_{GSO}	gate-source voltage	open drain	_	±20	V
R _{DSon}	drain-source on-state resistance	$I_D = 250 \text{ mA}; V_{GS} = 10 \text{ V}$	_	6	Ω
V_{GSoff}	gate-source cut-off voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$	0.8	2	V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DS}	drain-source voltage (DC)		_	300	V
V_{GSO}	gate-source voltage (DC)	open drain	_	±20	V
I _D	drain current (DC)		_	350	mA
I _{DM}	peak drain current		_	1.4	Α
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	1.5	W
T _{stg}	storage temperature		-55	+150	°C
T _j	junction temperature		_	150	°C

Note

1. Device mounted on an epoxy printed-circuit board, 40 x 40 x 1.5 mm, mounting pad for the drain tab minimum 6 cm².

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient; note 1	83.3	K/W

Note

1. Device mounted on an epoxy printed-circuit board, 40 x 40 x 1.5 mm, mounting pad for the drain tab minimum 6 cm².

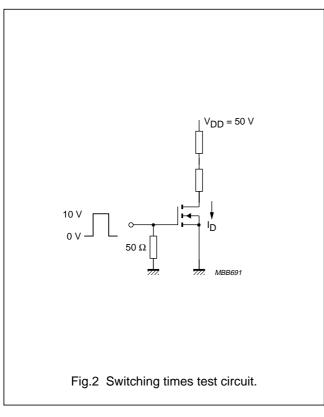
STATIC CHARACTERISTICS

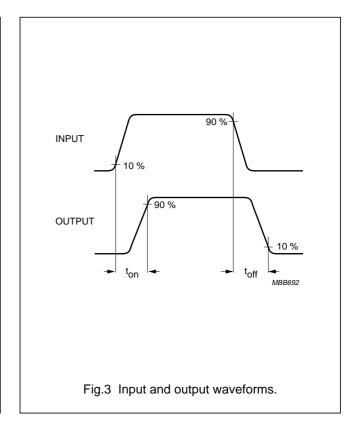
 $T_i = 25$ °C unless otherwise specified.

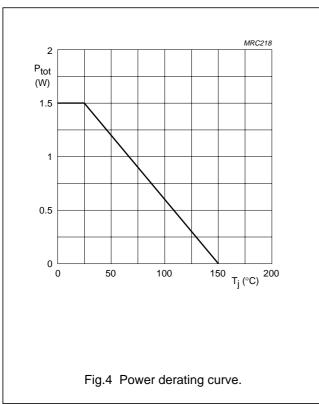
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
V _{(BR)DSS}	drain-source breakdown voltage	$I_D = 10 \mu\text{A}; V_{GS} = 0$	300	_	_	V	
I _{GSS}	gate-source leakage current	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0$	_	_	±100	nA	
V _{GSth}	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$	0.8	_	2	V	
R _{DSon}	drain-source on-state resistance	I _D = 20 mA; V _{GS} = 2.4 V	_	4.8	10	Ω	
		$I_D = 250 \text{ mA}; V_{GS} = 10 \text{ V}$	_	3.7	6	Ω	
I _{DSS}	drain-source leakage current	V _{DS} = 240 V; V _{GS} = 0	_	_	100	nA	
Y _{fs}	transfer admittance	I _D = 250 mA; V _{DS} = 25 V	200	690	_	mS	
C _{iss}	input capacitance	V _{DS} = 25 V; V _{GS} = 0; f = 1 MHz	_	100	120	pF	
C _{oss}	output capacitance	V _{DS} = 25 V; V _{GS} = 0; f = 1 MHz	_	21	30	pF	
C _{rss} feedback capacitance		V _{DS} = 25 V; V _{GS} = 0; f = 1 MHz	_	10	15	pF	
Switching times (see Figs 2 and 3)							
t _{on}	turn-on time	$I_D = 250 \text{ mA}; V_{DD} = 50 \text{ V};$ $V_{GS} = 0 \text{ to } 10 \text{ V}$	_	6	10	ns	
t _{off} turn-off time		$I_D = 250 \text{ mA}; V_{DD} = 50 \text{ V};$ $V_{GS} = 10 \text{ to } 0 \text{ V}$	_	46	60	ns	

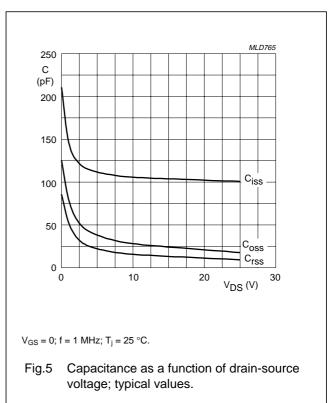
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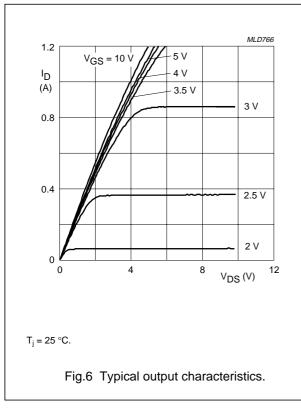


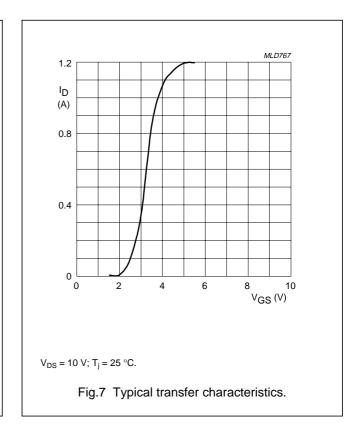


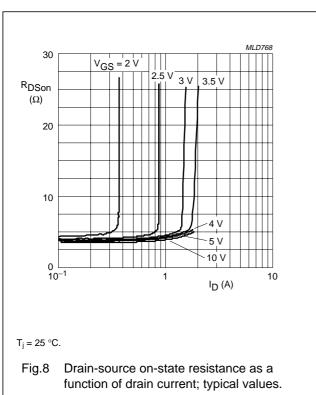


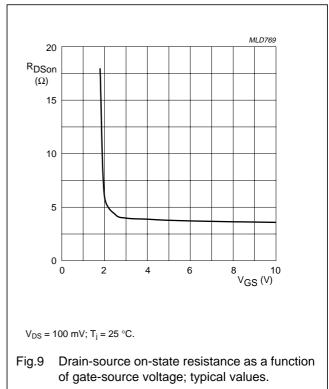
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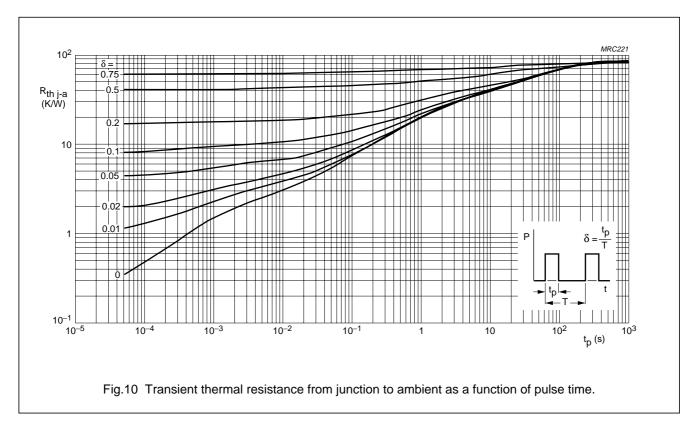


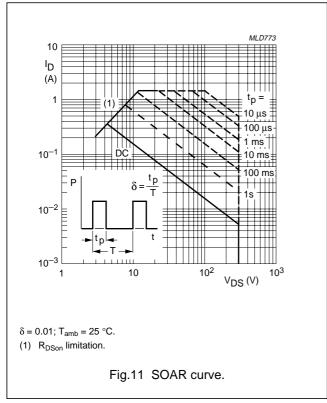




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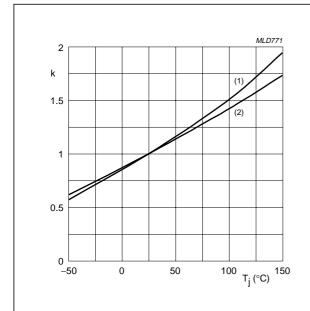
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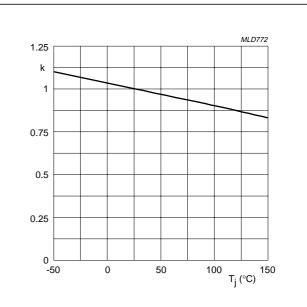
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$$k = \frac{R_{DS(on)} \text{ at } T_j}{R_{DS(on)} \text{at } 25 \, ^{\circ}\text{C}}$$

Typical R_{DSon}; (1) $I_D = 250$ mA; $V_{GS} = 10$ V. (2) $I_D = 20$ mA; $V_{GS} = 2.4$ V.

Fig.12 Temperature coefficient of drain-source on-state resistance; typical values.



$$k = \frac{V_{GS(th)} \text{ at } T_j}{V_{GS(th)} \text{ at 25 } ^{\circ}C}$$

Typical V_{GSth} at 1 mA.

Fig.13 Temperature coefficient of gate-source threshold voltage; typical values.

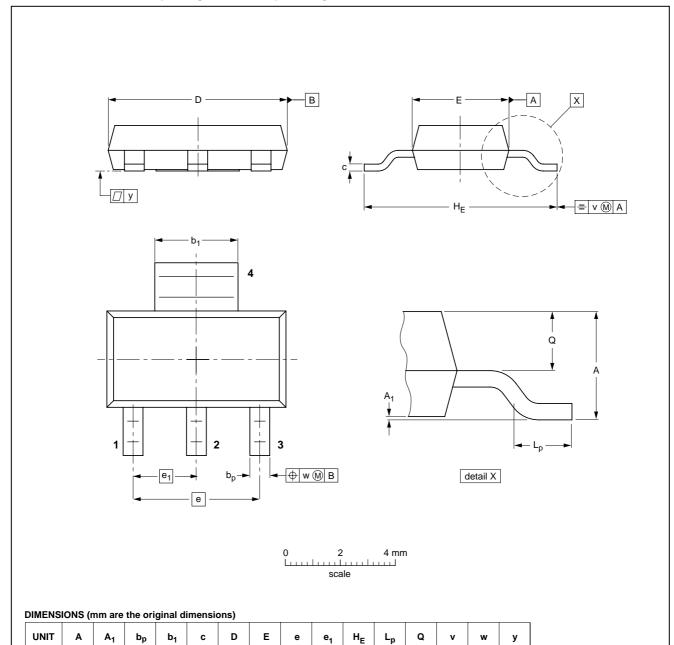
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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT223			SC-73		97-02-28 99-09-13

2.3

0.95

0.1

2001 Dec 11 8

0.32

0.22

6.7

3.7

0.10

0.01

0.80

0.60

2.9

1.8

1.5

mm

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DATA SHEET STATUS

DATA SHEET STATUS(1)	PRODUCT STATUS ⁽²⁾	DEFINITIONS
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NOTES

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NOTES

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Contact information

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